



COPY OF PAPERS  
ORIGINALLY FILED  
R070-98-CS

Feb. 28, 2002

TECHNOLOGY CENTER 2800  
MAR 21 2002

RECEIVED  
4-8-02

COPY OF PAPERS  
ORIGINALLY FILED

To: Commissioner of Patents and Trademarks  
Washington, D.C. 20231  
ATTN: Group Art Unit 2815 J. R. Diaz  
From: Stephen B. Ackerman, Reg. No. 37,761  
20 McIntosh Drive  
Poughkeepsie, N.Y. 12603

Serial No. 09/764,242 01/19/2001

Wong

A FILL PATTERN IN KERF AREAS TO PREVENT LOCALIZED  
NON-UNIFORMITIES OF INSULATING LAYERS AT DIE  
CORNERS ON SEMICONDUCTOR SUBSTRATES

Group Art Unit: 2815 J. R. Diaz

RESPONSE TO PATENT OFFICE ACTION

Dear Sir or Madam:

The Commissioner is hereby authorized to charge payment  
of any additional fees involved with added Claims and the  
like to Deposit Account No. 19-0033.

In response to Office Action dated Dec. 5, 2001, please  
amend the above identified application for patent as  
follows, and please consider the following remarks.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
deposited with the U. S. Postal Service as first class mail  
in an envelope addressed to: Commissioner of Patents and  
Trademarks, Washington, D.C. 20231, on March 5, 2002.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date 3/5/02